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plant



Bypass Thyristor

Provisional Information

DS6189-2 August 2016 (LN33711)

KEY PARAMETERS

V_{DRM} V_{RRM}

I_{T(AV)}

I_{⊤sм} dV/dt 1000V

3300V

3200A

43000A

10kV/µs

FEATURES

- Double Side Cooling
- High Surge Capability
- Very Low Cosmic Ray FIT Rating
- High dv/dt Rating

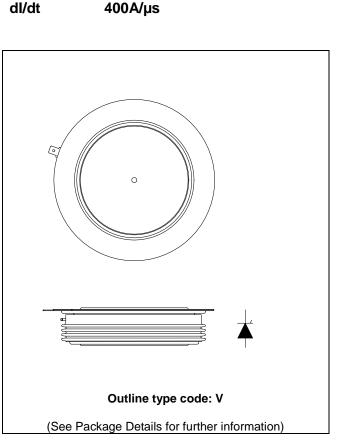


Fig. 1 Package outline

APPLICATIONS

• Multi-level VSC By-pass thyristor for HVDC

VOLTAGE RATINGS

Part and Ordering Number	Repetitive Peak Voltages V _{DRM} and V _{RRM} V	Conditions
ACR3200VR33	1000 / 3300	$ T_{vj} = -40^{\circ}C \text{ to } 125^{\circ}C, \\ I_{DRM} = I_{RRM} = 400\text{mA}, \\ V_{DRM}, V_{RRM} t_p = 10\text{ms}, $

ORDERING INFORMATION

For example:

ACR3200VR33

Note: Please use the complete part number when ordering and quote this number in any future correspondence relating to your order.





CURRENT RATINGS

T_{case} = 60°C unless stated otherwise

Symbol	Parameter	Test Conditions	Max.	Units
Double Sid	de Cooled			
I _{T(AV)}	Mean on-state current	Half wave resistive load	3200	А
I _{T(RMS)}	RMS value	-	5026	А
Ι _Τ	Continuous (direct) on-state current	-	4900	А

SURGE RATINGS

Symbol	Parameter	Test Conditions	Max.	Units
I _{TSM}	Surge (non-repetitive) on-state current	10ms half sine, $T_{case} = 125^{\circ}C$	43	kA
l ² t	I ² t for fusing	$V_R = 0$	9.24	MA ² s

THERMAL AND MECHANICAL RATINGS

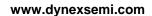
Symbol	Parameter	Test Condition	S	Min.	Max.	Units
R _{th(j-c)}	Thermal resistance – junction to case	Double side cooled	DC	-	0.00746	°C/W
		Single side cooled	Anode DC	-	0.0130	°C/W
			Cathode DC	-	0.0178	°C/W
R _{th(c-h)}	Thermal resistance – case to heatsink	Clamping force 54kN	Double side	-	0.002	°C/W
		(with mounting compound)	Single side	-	0.004	°C/W
T_{vj}	Virtual junction temperature	Blocking V _{DRM} / V _{RRM}		-	125	°C
T _{stg}	Storage temperature range			-55	125	°C
F _m	Clamping force			48.0	59.0	kN





DYNAMIC CHARACTERISTICS

Symbol	Parameter	Test Conditio	ns	Min.	Max.	Units
I _{RRM} /I _{DRM}	Peak reverse and off-state current	At V _{RRM} /V _{DRM} , T _{case} = 125°C		-	400	mA
dV/dt	Max. linear rate of rise of off-state voltage	To 67% V_{DRM} , $T_j = 60^{\circ}C$, gate	e open circuit	-	10000	V/µs
dl/dt	Rate of rise of on-state current	From 67% V _{DRM} to 2x I _{T(AV)} Gate source 30V, 10 Ω , t _r < 0.5µs, T _j = 125°C	Non-repetitive	-	400	A/µs
V _{T(TO)}	Threshold voltage – Low level	300A to 2400A at $T_{case} = 125$	5°C	-	0.8383	V
	Threshold voltage – High level	2400A to 9000A at $T_{case} = 12$	25°C	-	1.0419	V
r _T	On-state slope resistance – Low level	300A to 2400A at $T_{case} = 125$	5°C	-	0.2374	mΩ
	On-state slope resistance – High level	2400A to 9000A at $T_{case} = 12$	25°C	-	0.1490	mΩ
t _{gd}	Delay time	$V_D = 67\% V_{DRM}, I_g=3A,$ $t_r = 0.5 \mu s, T_j = 25^{\circ}C, t_p = 40 \mu$	S	3	3	μs
DC FITs	DC Cosmic Ray FIT Rating	$T_j = 25^{\circ}C, V_R = 50\% V_{RRM}, set$	ea level		24	Per 10 ⁹
		$T_j = 25^{\circ}C, V_R = 67\% V_{RRM}$, se	ea level		743	hours
Vpu	Pick-up Voltage	$I_g=3A, t_r = 0.5\mu s, T_j = 25^{\circ}C, t_j$	_o = 40µs		2	V
ΙL	Latching current	$T_j = 25^{\circ}C, V_D = 5V$		-	3	А
I _H	Holding current	$T_j = 25^{\circ}C, R_{G-K} = \infty, I_{TM} = 500$	0A, I _T = 5A	-	300	mA

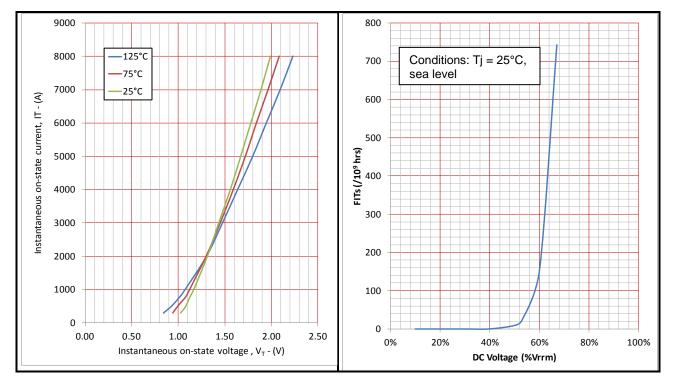


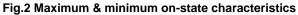
GATE TRIGGER CHARACTERISTICS AND RATINGS

Symbol	Parameter	Test Conditions	Max.	Units
V _{GT}	Gate trigger voltage	$V_{DRM} = 5V, T_{case} = 25^{\circ}C$	1.5	V
V _{GD}	Gate non-trigger voltage	At V _{DRM} , T _{case} = 125°C	TBD	V
I _{GT}	Gate trigger current	$V_{DRM} = 5V, T_{case} = 25^{\circ}C$	350	mA
I _{GD}	Gate non-trigger current	$V_{DRM} = 5V, T_{case} = 25^{\circ}C$	TBD	mA

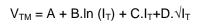
CURVES

SEMICONDUCTOR





V_{TM} EQUATION



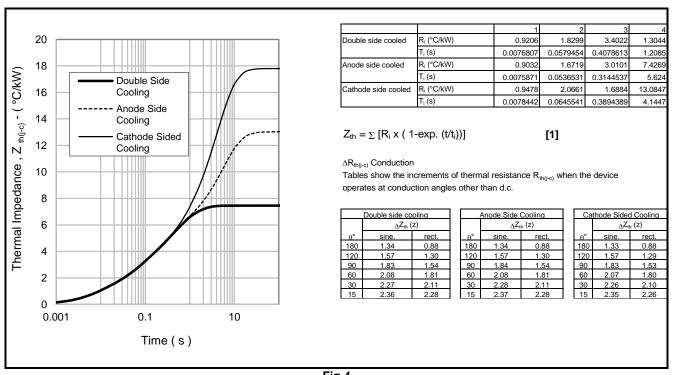
Where A = -0.303672B = 0.216168C = 0.000164D = -0.007999

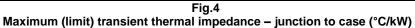
these values are valid for T_j = 125°C for I_T 300A to 9000

Fig.3 Cosmic Ray DC FIT Rating









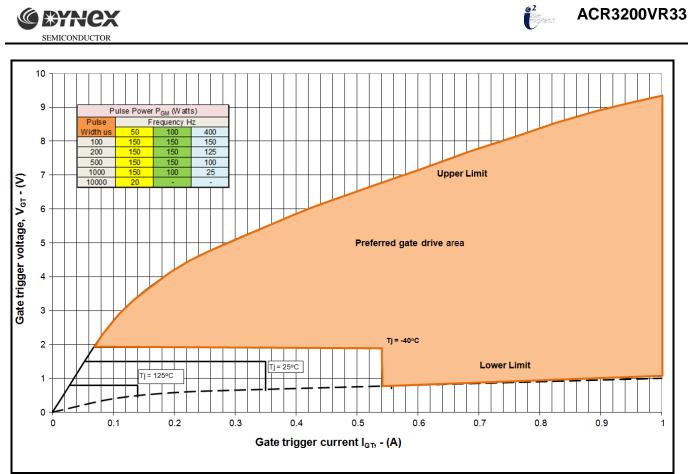


Fig5 Gate Characteristics

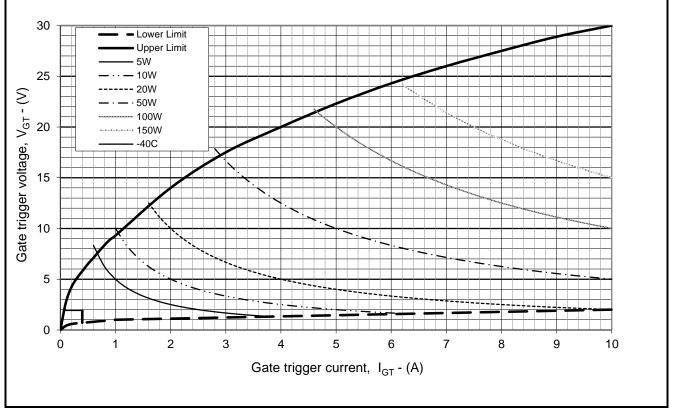


Fig. 6 Gate characteristics



PACKAGE DETAILS

For further package information, please contact Customer Services. All dimensions in mm, unless stated otherwise. DO NOT SCALE.

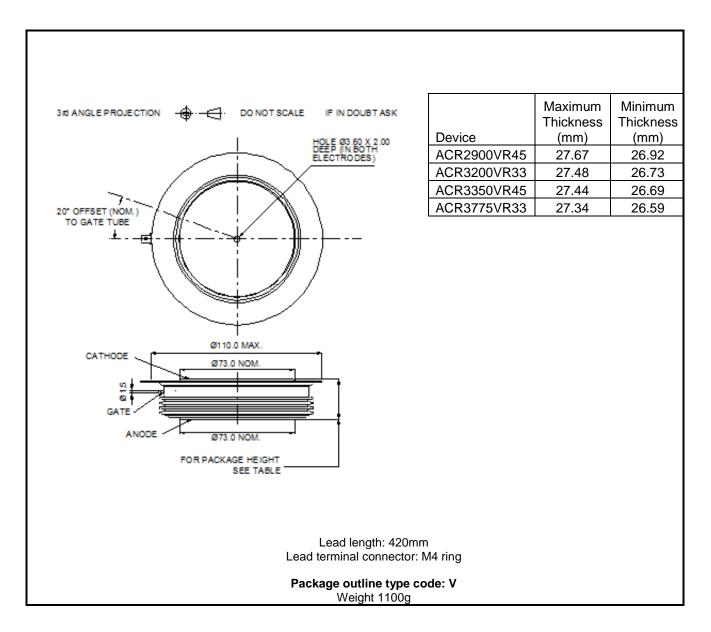


Fig.7 Package outline





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